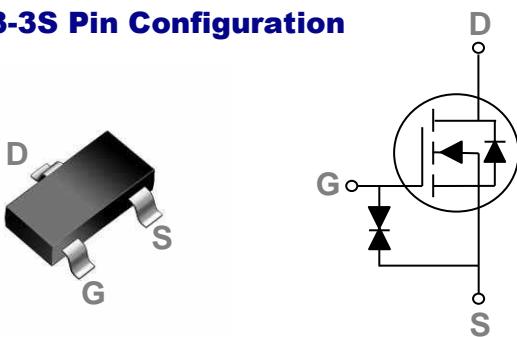


General Description

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

SOT23-3S Pin Configuration



BVDSS	RDS(ON)	ID
60V	3Ω	0.2A

Features

- 60V,0.2A, RDS(ON) =3Ω@VGS=10V
- Improved dv/dt capability
- Fast switching
- 100% EAS Guaranteed
- Green Device Available
- G-S ESD Protection Diode Embedded
- ESD protected up to 2KV

Applications

- Motor Drive
- Power Tools
- LED Lighting

Absolute Maximum Ratings $T_c=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	60	V
V_{GS}	Gate-Source Voltage	± 20	V
I_D	Drain Current – Continuous ($T_A=25^\circ\text{C}$)	0.2	A
	Drain Current – Continuous ($T_A=70^\circ\text{C}$)	0.16	A
I_{DM}	Drain Current – Pulsed ¹	0.8	A
P_D	Power Dissipation ($T_A=25^\circ\text{C}$)	0.35	W
	Power Dissipation – Derate above 25°C	0.003	W/°C
T_{STG}	Storage Temperature Range	-55 to 150	°C
T_J	Operating Junction Temperature Range	-55 to 150	°C

Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction to ambient	---	357	°C/W

Electrical Characteristics ($T_J=25\text{ }^{\circ}\text{C}$, unless otherwise noted)
Off Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$, $I_D=250\mu\text{A}$	60	---	---	V
I_{DSS}	Drain-Source Leakage Current	$V_{DS}=60\text{V}$, $V_{GS}=0\text{V}$, $T_J=25\text{ }^{\circ}\text{C}$	---	---	1	μA
		$V_{DS}=48\text{V}$, $V_{GS}=0\text{V}$, $T_J=125\text{ }^{\circ}\text{C}$	---	---	10	μA
I_{GSS}	Gate-Source Leakage Current	$V_{GS}=\pm 20\text{V}$, $V_{DS}=0\text{V}$	---	---	± 20	μA

On Characteristics

$R_{DS(\text{ON})}$	Static Drain-Source On-Resistance	$V_{GS}=10\text{V}$, $I_D=0.2\text{A}$	---	1.3	3	Ω
		$V_{GS}=4.5\text{V}$, $I_D=0.1\text{A}$	---	1.5	4	Ω
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{GS}=V_{DS}$, $I_D = 250\mu\text{A}$	1	1.8	2.5	V
g_{fs}	Forward Transconductance	$V_{DS}=10\text{V}$, $I_D=0.2\text{A}$	---	0.5	---	S

Dynamic and switching Characteristics

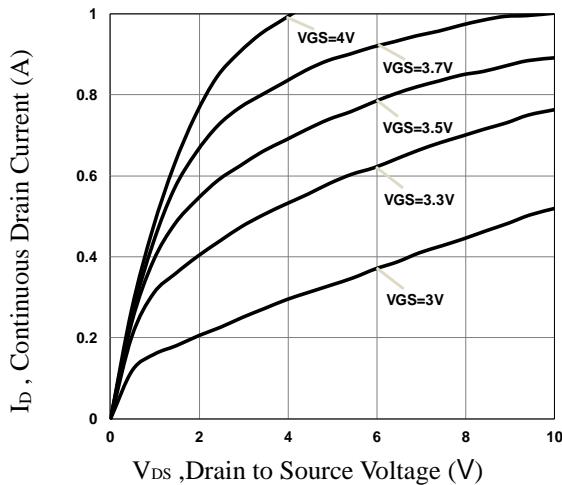
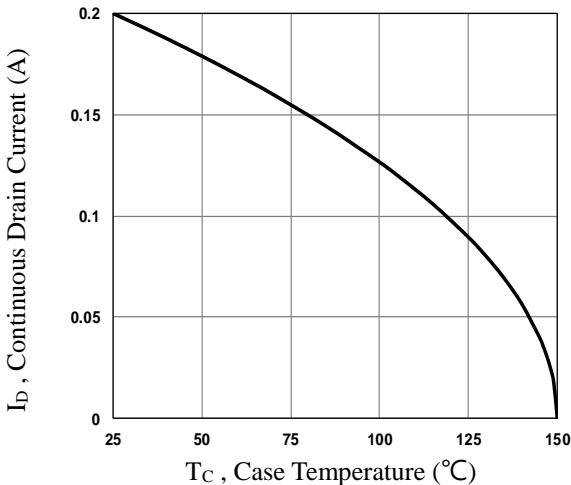
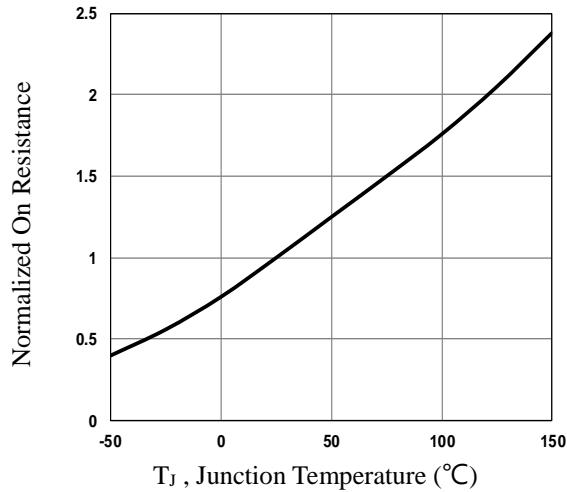
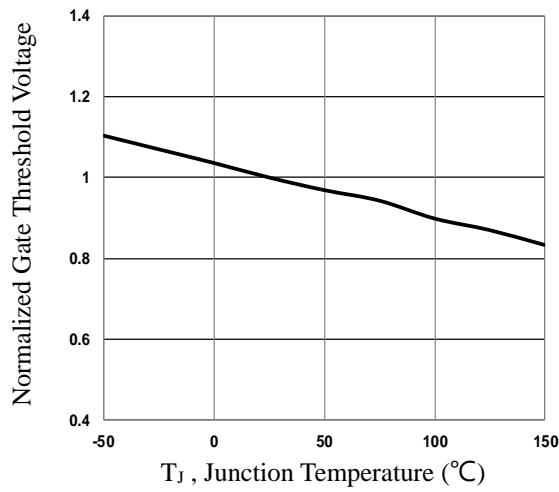
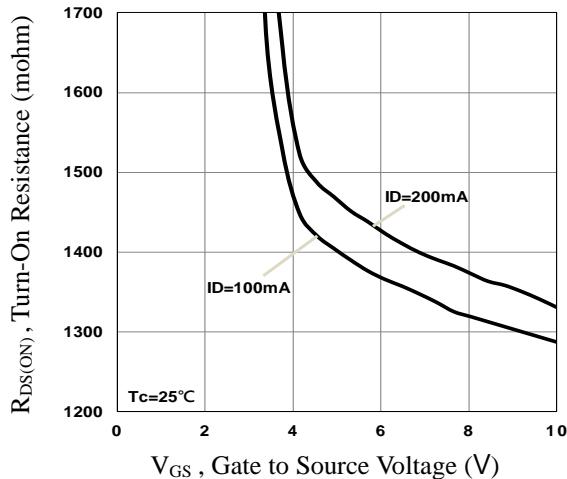
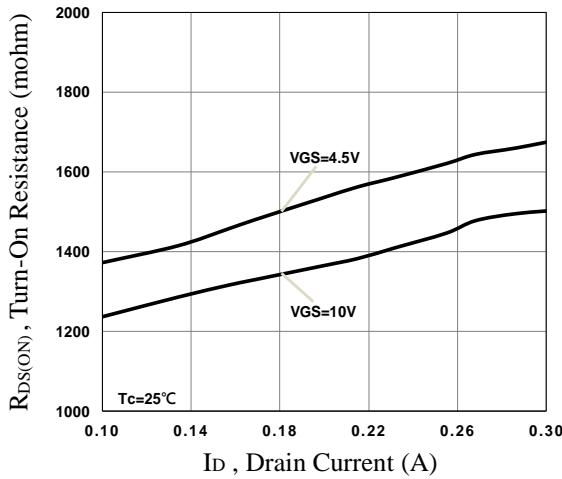
Q_g	Total Gate Charge ^{2, 3}	$V_{DS}=30\text{V}$, $V_{GS}=10\text{V}$, $I_D=0.2\text{A}$	---	3.7	5.6	nC
Q_{gs}	Gate-Source Charge ^{2, 3}		---	0.9	1.4	
Q_{gd}	Gate-Drain Charge ^{2, 3}		---	0.4	0.6	
$T_{d(on)}$	Turn-On Delay Time ^{2, 3}	$V_{DD}=30\text{V}$, $V_{GS}=10\text{V}$, $R_G=6\Omega$ $I_D=0.2\text{A}$	---	3	6	ns
T_r	Rise Time ^{2, 3}		---	5	10	
$T_{d(off)}$	Turn-Off Delay Time ^{2, 3}		---	14	27	
T_f	Fall Time ^{2, 3}		---	9	17	
C_{iss}	Input Capacitance	$V_{DS}=30\text{V}$, $V_{GS}=0\text{V}$, $F=1\text{MHz}$	---	25.5	38	pF
C_{oss}	Output Capacitance		---	17	26	
C_{rss}	Reverse Transfer Capacitance		---	7.8	12	

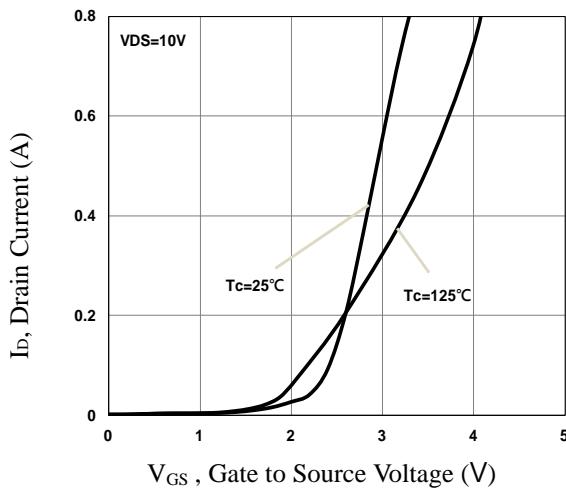
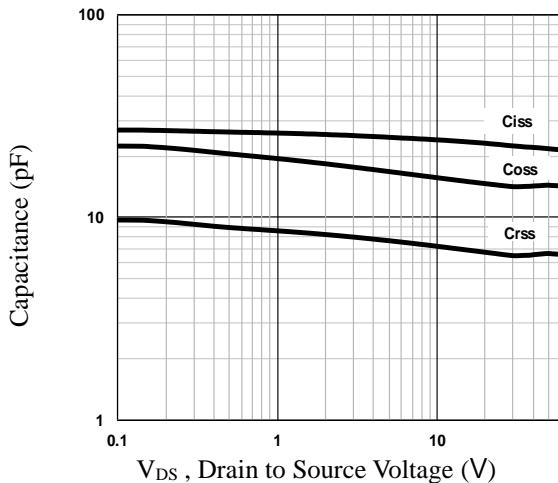
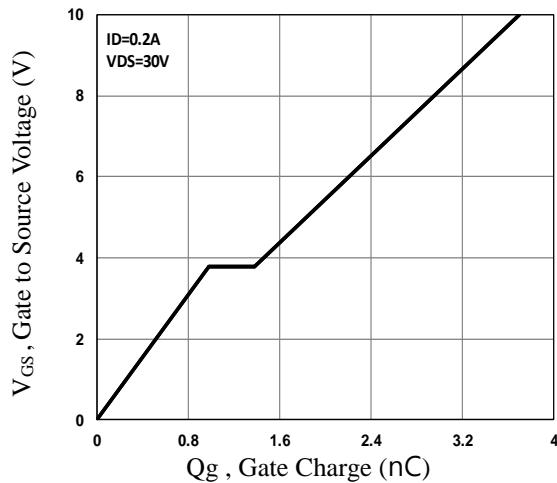
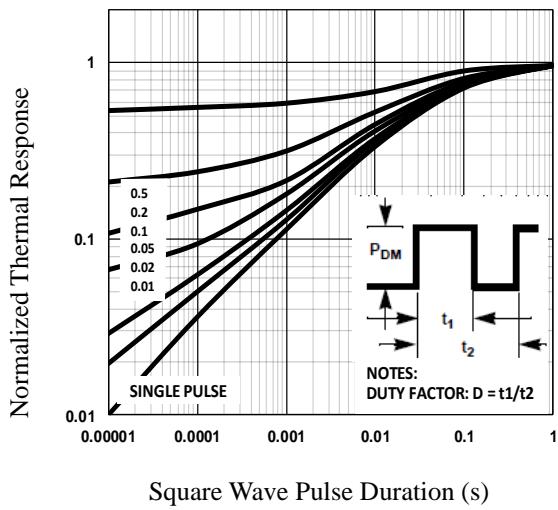
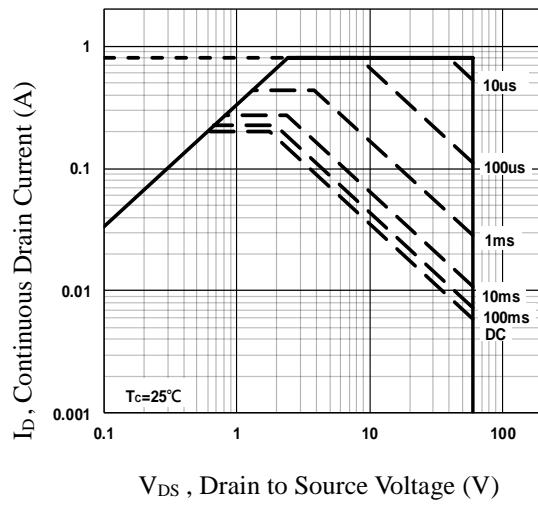
Drain-Source Diode Characteristics and Maximum Ratings

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_s	Continuous Source Current	$V_G=V_D=0\text{V}$, Force Current	---	---	0.2	A
			---	---	0.4	A
V_{SD}	Diode Forward Voltage	$V_{GS}=0\text{V}$, $I_s=0.2\text{A}$, $T_J=25\text{ }^{\circ}\text{C}$	---	---	1	V
t_{rr}	Reverse Recovery Time	$V_R=50\text{V}$, $I_s=0.2\text{A}$ $dI/dt=100\text{A}/\mu\text{s}$, $T_J=25\text{ }^{\circ}\text{C}$	---	3.4	---	ns
Q_{rr}	Reverse Recovery Charge		---	0.7	---	nC

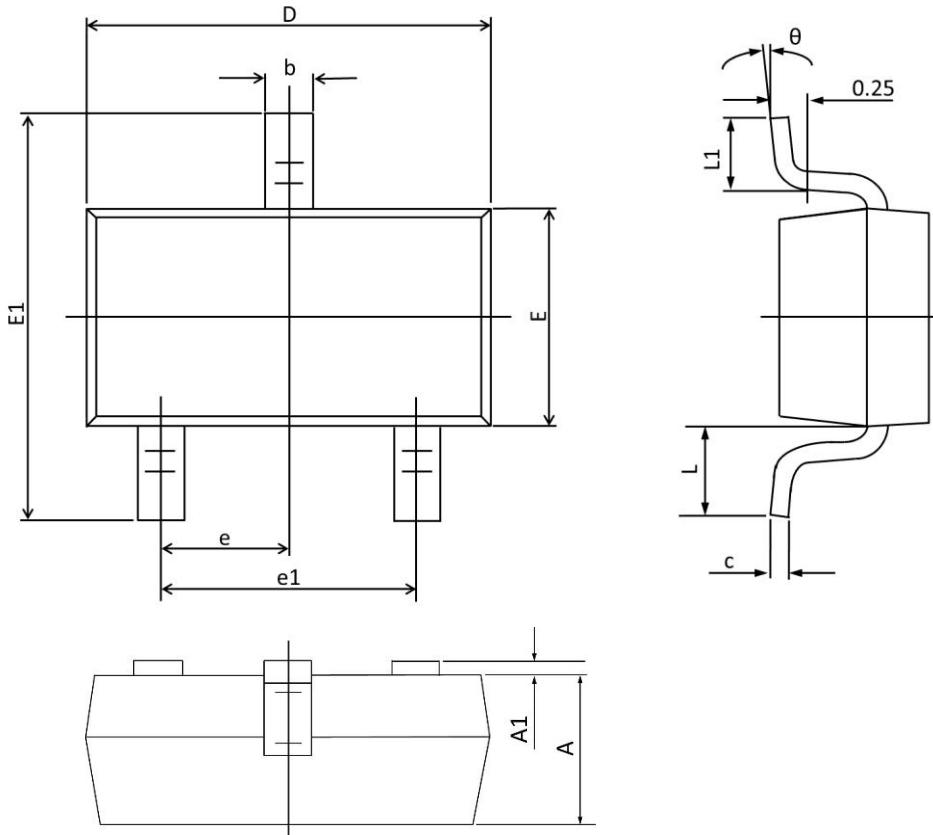
Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed , pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$.
3. Essentially independent of operating temperature.


Fig.1 Typical Output Characteristics

Fig.2 Continuous Drain Current vs. T_c

Fig.3 Normalized $R_{DS(on)}$ vs. T_j

Fig.4 Normalized V_{th} vs. T_j

Fig.5 Turn-On Resistance vs. V_{GS}

Fig.6 Turn-On Resistance vs. I_D


Fig.7 Transfer Characteristics

Fig.8 Capacitance Characteristics

Fig.9 Gate Charge Characteristics

Fig.10 Normalized Transient

Fig.11 Maximum Safe Operation Area

SOT23-3S PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.900	1.150	0.035	0.045
A1	0.001	0.100	0.000	0.004
b	0.300	0.500	0.012	0.020
c	0.080	0.180	0.003	0.008
D	2.700	3.100	0.106	0.122
E	1.100	1.500	0.043	0.059
E1	2.100	2.640	0.080	0.104
e	0.950 TYP.		0.037 TYP.	
e1	1.780	2.040	0.070	0.080
L	0.550 REF.		0.022 REF.	
L1	0.100	0.500	0.004	0.020
θ	1°	10°	1°	10°